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**Sectional specification for high density interconnect printed
boards**

高密度互连印制板分规范

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Foreword

This document is in accordance with the provisions of GB/T 1.1-2020 "Guidelines for standardization work Part 1: Structure and drafting rules for standardization documents" Drafting.

Please note that some of the contents of this document may involve patents. The issuing organization of this document does not assume the responsibility for identifying patents.

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This document was drafted by: China Electronics Technology Group Corporation No. 15 Research Institute, Putian Hanjiang District Yiton Multilayer Circuit Co., Ltd., Guangzhou Guanghe Technology Co., Ltd., China Electronics Technology Standardization Institute, and Xiamen Bolian Technology Co., Ltd.

The main drafters of this document are: Guo Xiaoyu, Liu Shengxian, Peng Jinghui, Tang Ruifang, Tian Ling, Zeng Hong, Chen Changsheng, Lou Yafen, Cao Yi, and Wu Yongjin.

Sectional specification for high density interconnect printed boards

1 Scope

This document specifies application classes, performance requirements, quality assurance specifications, and delivery requirements for high density interconnect printed boards.

This document applies to high density interconnect printed boards with microvias.

2 Normative references

GB/T 2036

GB/T 4588.4-2017

GB/T 4677-2002

GB/T 16261-2017

GB/T 18334

GB/T 18335

3 Terms and definitions

The terms and definitions defined in GB/T 2036 and SJ/T 10668 and the following apply to this document.

3.1 $\leq 0.15\text{mm}$, minimum wire width and spacing $\leq 100\mu\text{m}$

An interconnected circuit with an average of not less than 20 electrical connections per square centimeter on one or both sides of a printed circuit board.

Note. High-density interconnected printed boards are usually produced using a build-up process, with microvias and/or vias used for electrical interconnection between layers. The minimum aperture is

3.2 Microvia

The ratio of hole depth (X) to hole diameter (Y) is not greater than 1, and the distance from the capture pad to the target pad (same hole depth) does not exceed 0.25mm Blind hole.

Note. As shown in Figure 1.